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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

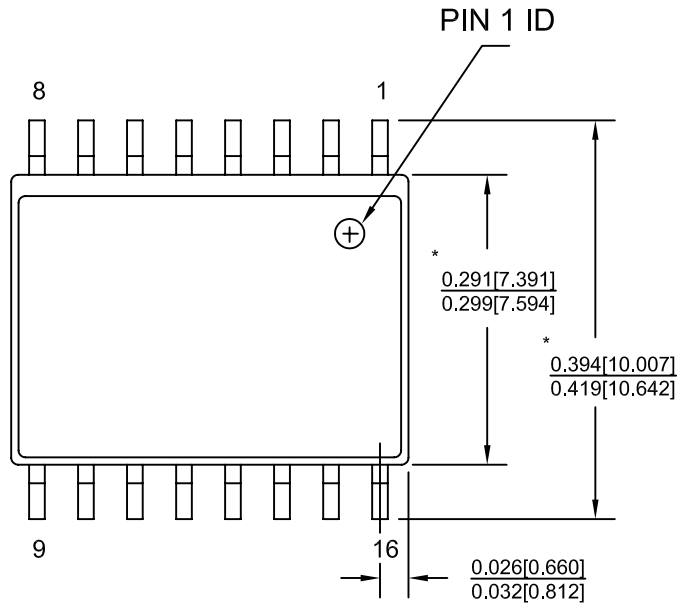
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

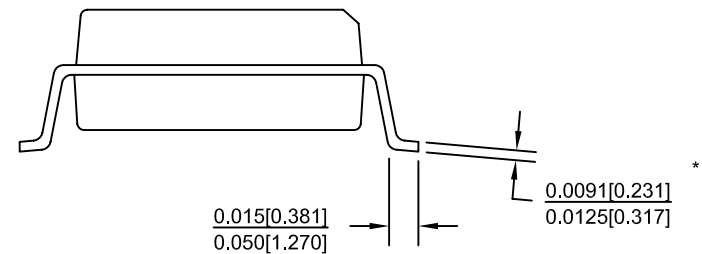
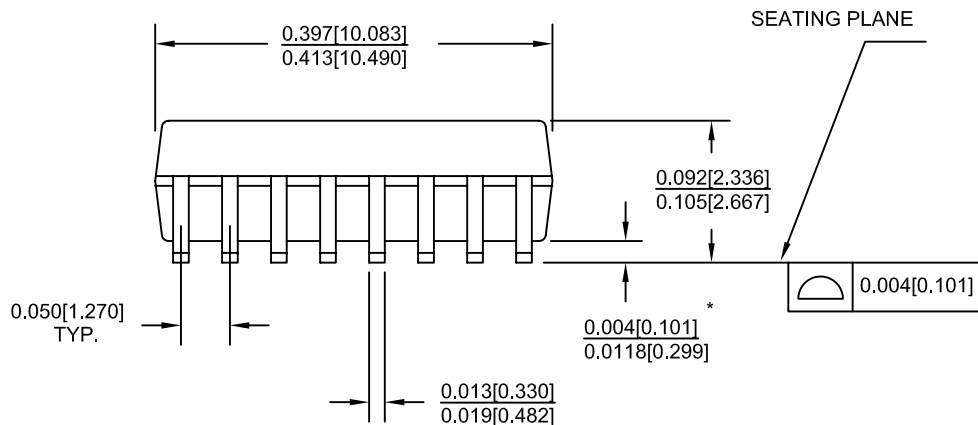
16 Lead (300 Mil) SOIC - S1



DIMENSIONS IN INCHES[MM] MIN.
MAX.

REFERENCE JEDEC MO-119

PART #	
S16.3	STANDARD PKG.
SZ16.3	LEAD FREE PKG.



TITLE
PACKAGE OUTLINE, 16L SOIC .413X.299X.0932 INCHES


SPEC NO. 51-85022 REV *E

SCALE: 1:1 SHEET 1 OF 2

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PACKAGE CODE(S) SEE NOTE

Rev.	ECN No.	Origin of Change	Description of Change
**	N/A	N/A	N/A
*A	49379	HTN	CHG. TITLE/ CHG. DIM.S AT *
*B	128905	DTOL	ADD MM DIM./ADD JEDEC #/ADD SZ PART #.
*C	2868899	TZWTMP3	CHANGED TEMPLATE, CHANGE TITLE FROM 16LD (300 MIL) SOIC PKG OUTLINE TO PACKAGE OUTLINE, 16L SOIC .413X.299X.0932 INCHES
*D	3252179	QADTMP1	NO CHANGE
*E	3924358	EDCA	SUNSET REVIEW. UPDATED TEMPLATE.

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, 16L SOIC .413X.299X.0932 INCHES	
SPEC NO. 51-85022	REV *E
SCALE: 1:1	SHEET 2 OF 2

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PACKAGE CODE(S)

SEE NOTE